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Park et al.

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(54) **MULTILAYER CERAMIC CAPACITOR AND MANUFACTURING METHOD THEREOF**

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H01G 2/06 (2006.01)

H01G 4/012 (2006.01)

(52) **U.S. Cl.**

CPC **H01G 2/065** (2013.01); **H01G 4/012** (2013.01); **H01G 4/30** (2013.01)

(58) **Field of Classification Search**

CPC H01G 4/30; H01G 4/012

USPC 361/301.4, 306.1, 306.3, 311–313, 361/321.1, 321.22

See application file for complete search history.

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Primary Examiner — Nguyen T Ha

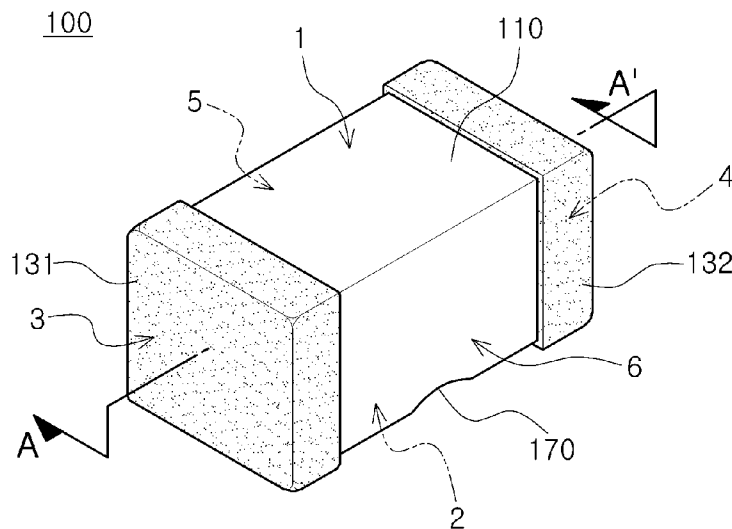
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(57)

ABSTRACT

There is provided a multilayer ceramic capacitor including, a ceramic body having a plurality dielectric layers stacked therein and a groove portion recessed inwardly in a lower surface thereof in a width direction, a plurality of first and second internal electrodes disposed in the ceramic body to be alternately exposed through both end surfaces of the ceramic body, having the dielectric layers therebetween, and first and second external electrodes respectively formed on both end portions of the ceramic body and electrically connected to the first and second internal electrodes, respectively.

21 Claims, 11 Drawing Sheets



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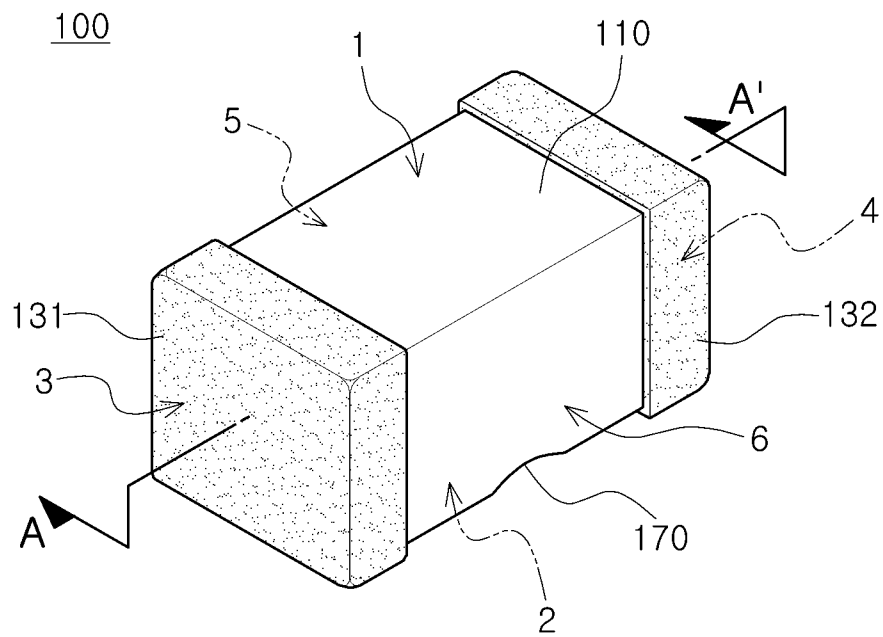


FIG. 1

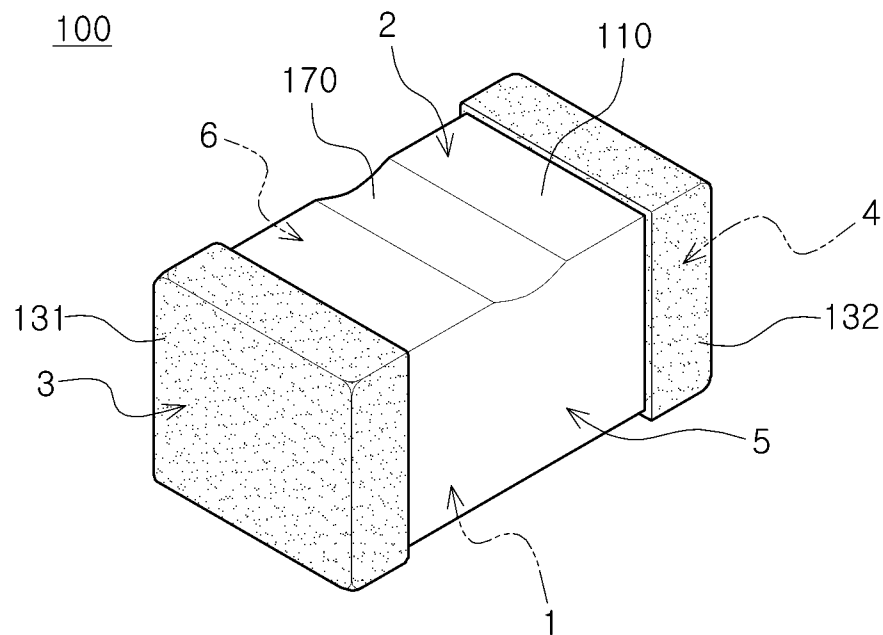


FIG. 2

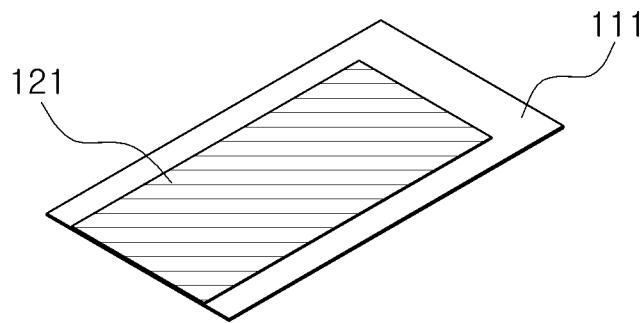


FIG. 3A

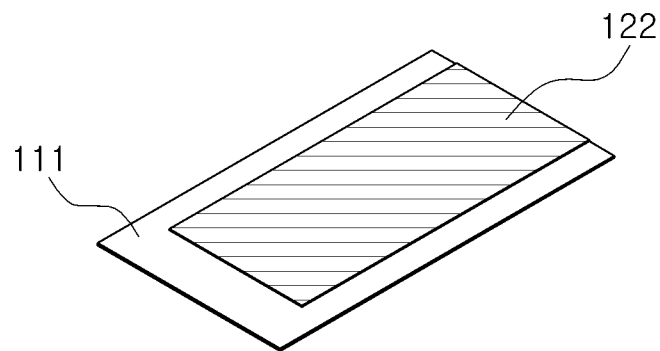


FIG. 3B

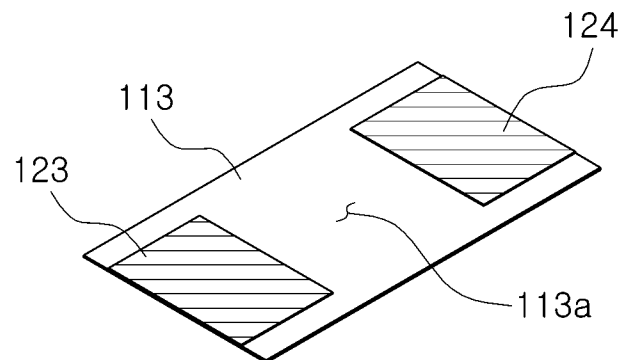


FIG. 3C

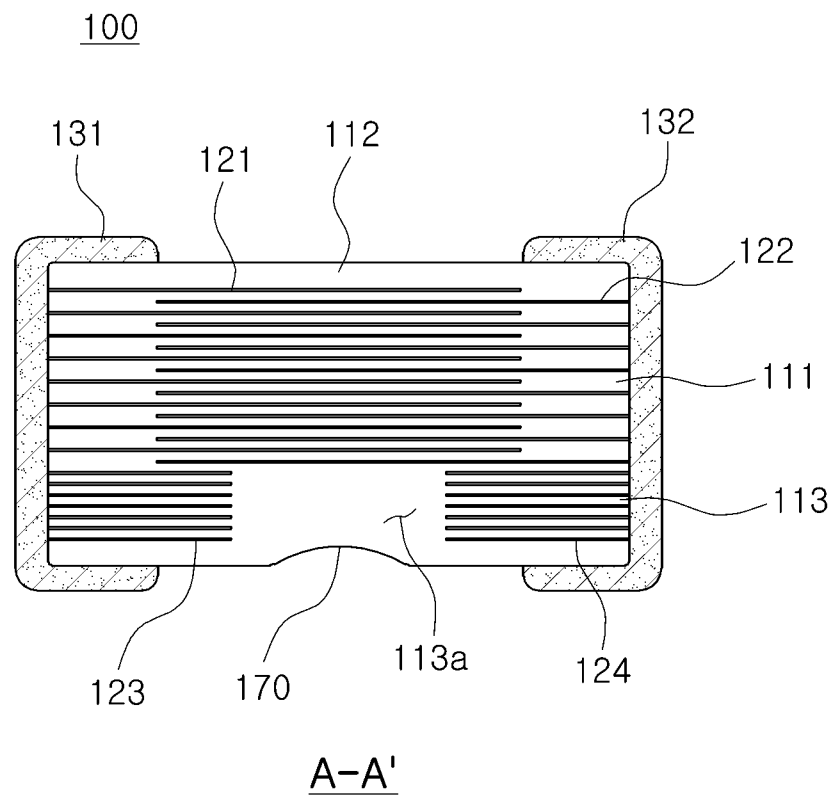


FIG. 4

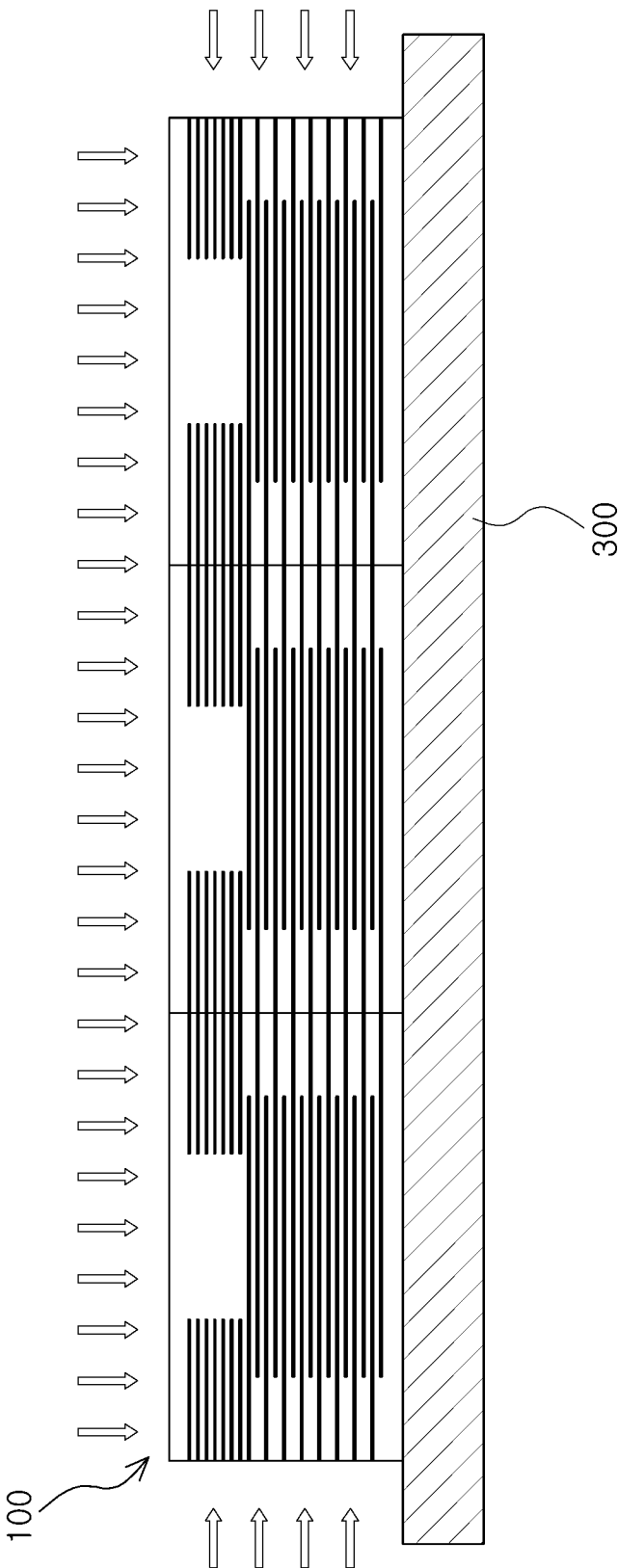


FIG. 5A

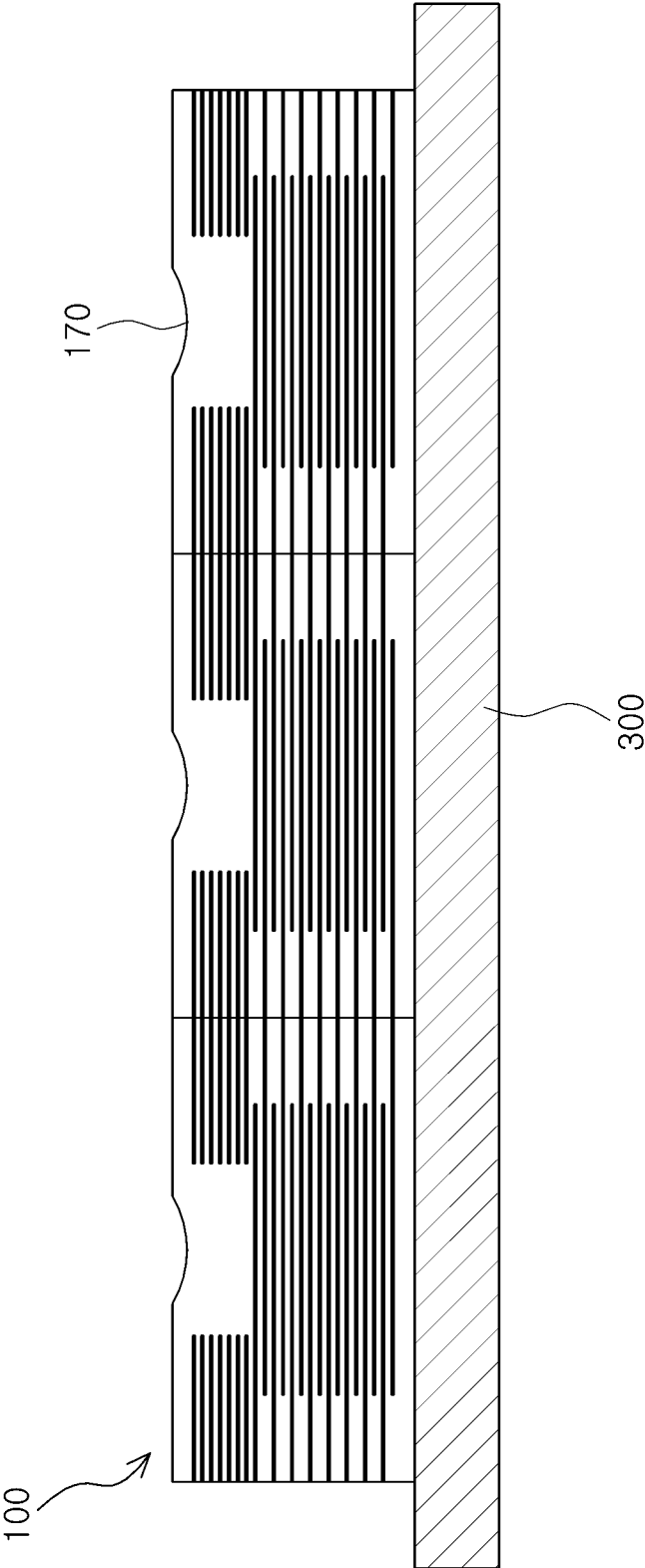


FIG. 5B

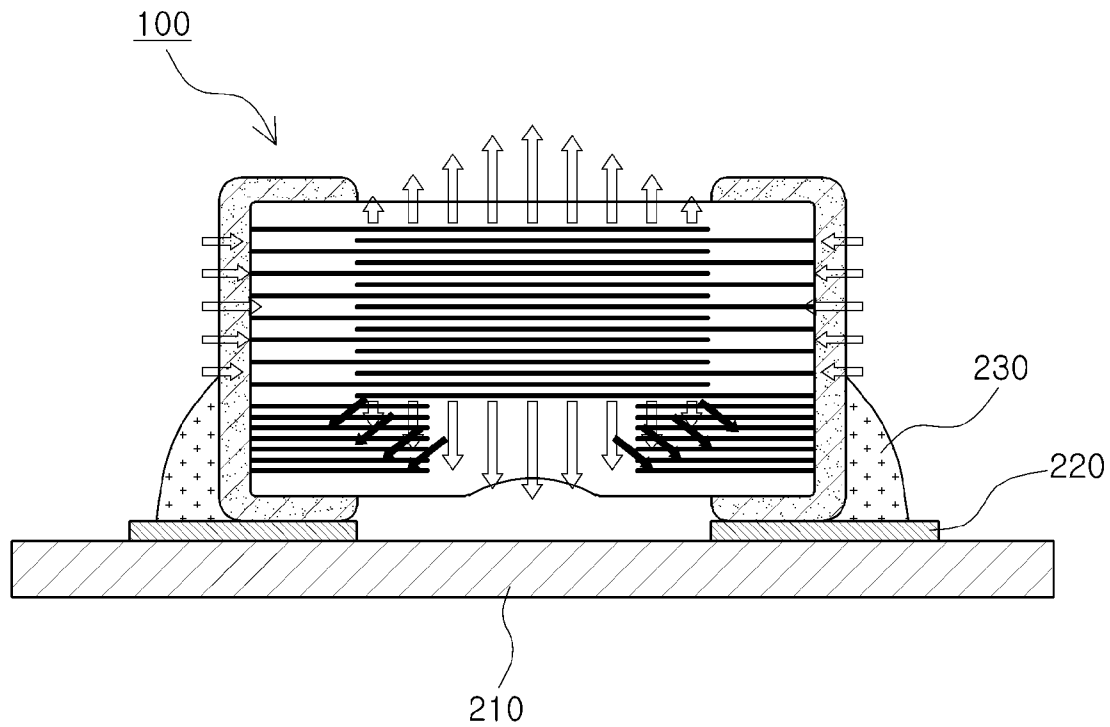


FIG. 6

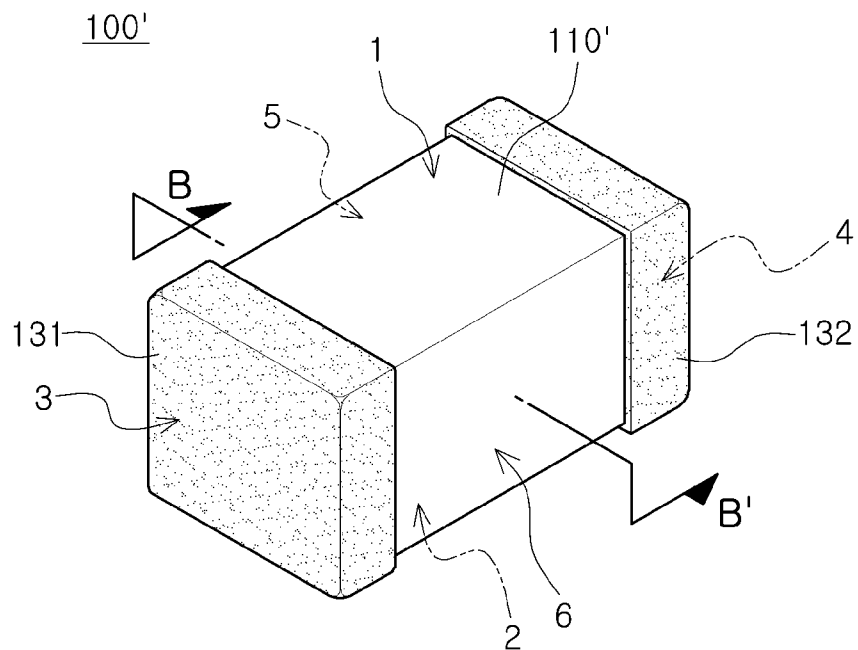


FIG. 7

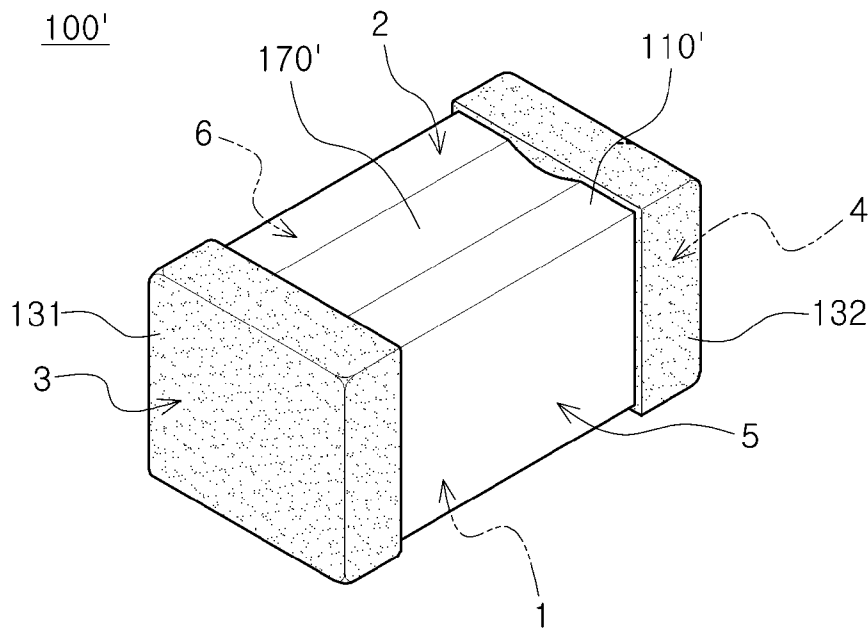
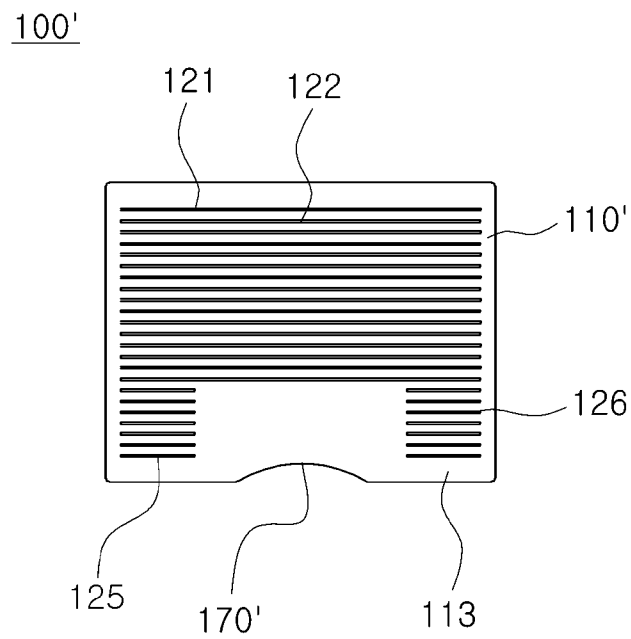


FIG. 8



B-B'

FIG. 9

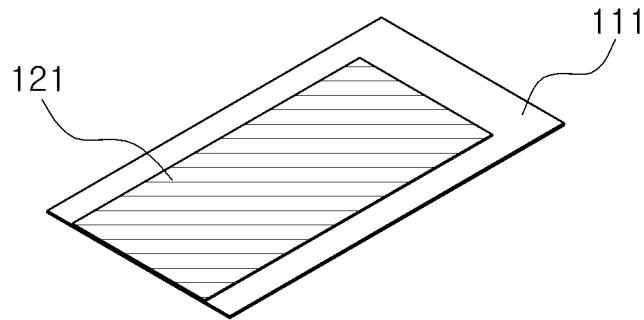


FIG. 10A

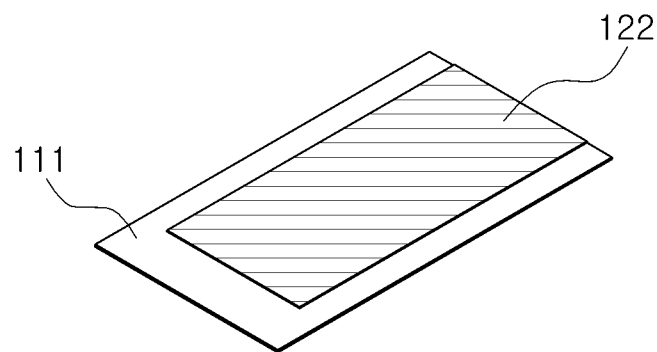


FIG. 10B

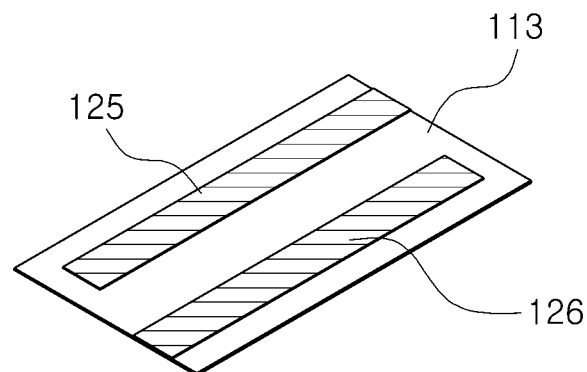


FIG. 10C

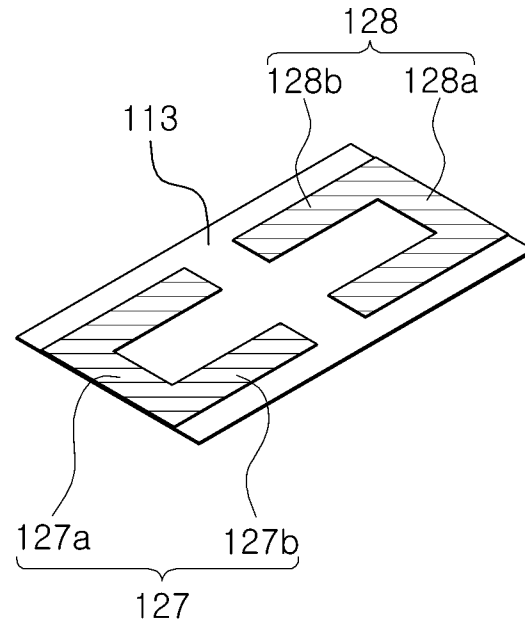


FIG. 11

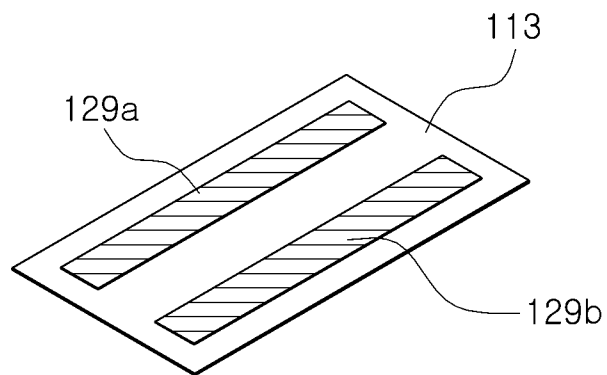


FIG. 12

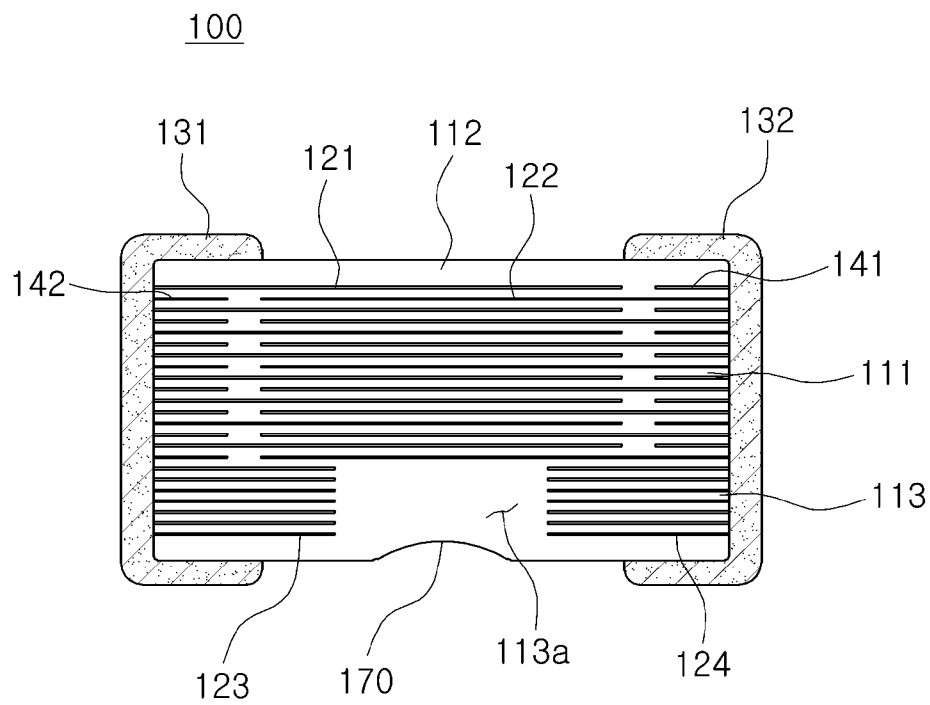


FIG. 13

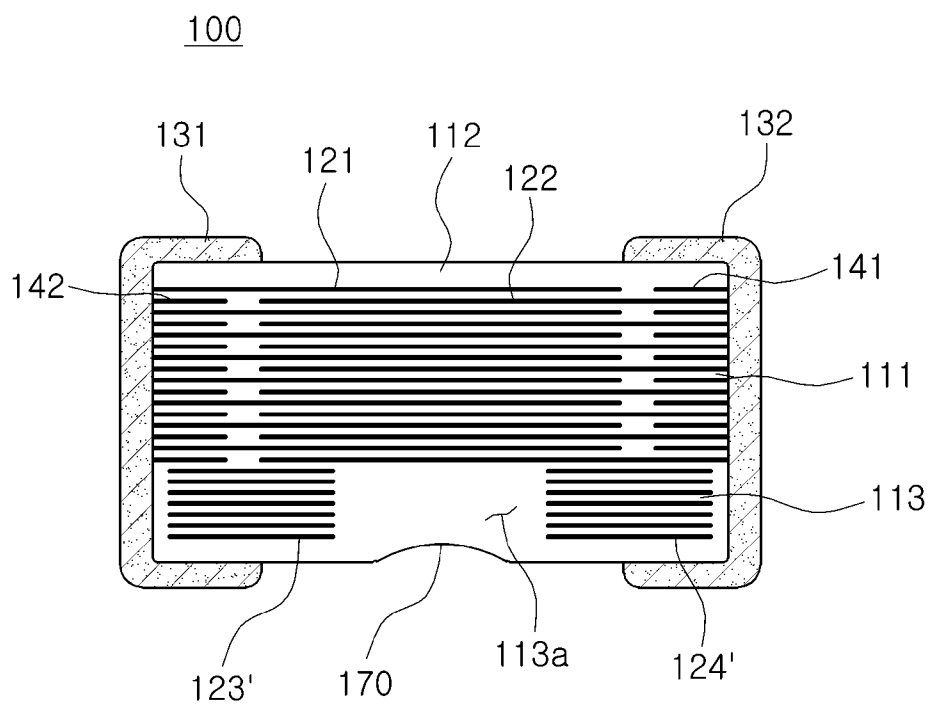


FIG. 14

100"

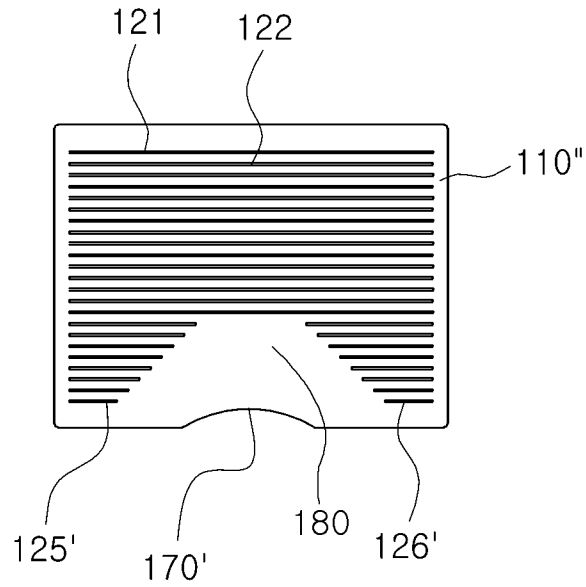


FIG. 15

100"

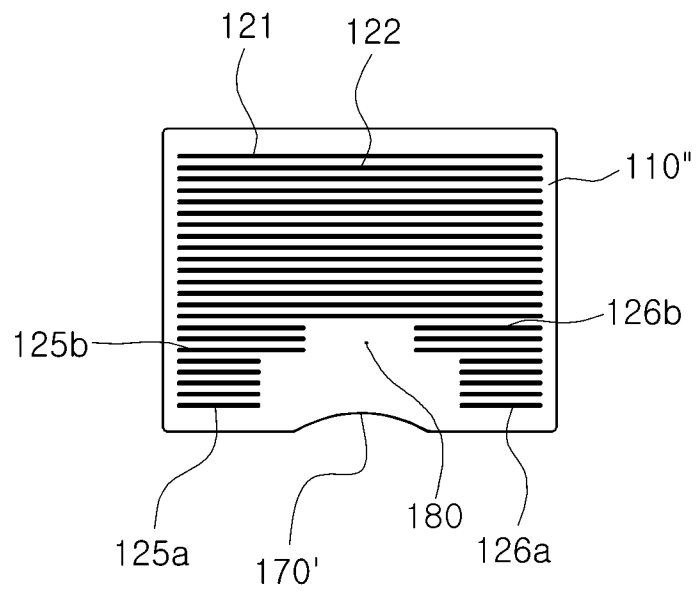


FIG. 16

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MULTILAYER CERAMIC CAPACITOR AND MANUFACTURING METHOD THEREOF

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims the benefit of Korean Patent Application No. 10-2013-0081745 filed on Jul. 11, 2013, with the Korean Intellectual Property Office, the disclosure of which is incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a multilayer ceramic capacitor and a manufacturing method thereof.

2. Description of the Related Art

A multilayer ceramic capacitor (MLCC), a multilayer chip electronic component, is capable of being used in various electronic devices, due to advantages such as a small size, high capacitance, ease of mounting, or the like.

For example, the multilayer ceramic capacitor is used in a chip-shaped condenser mounted on printed circuit boards of various electronic products including display devices, liquid crystal displays (LCDs), plasma display panels (PDPs) and the like, for example, as well as including computers, smartphones, mobile phones, and the like, to serve to charge and discharge electricity therein.

The multilayer ceramic capacitor may have a structure in which a plurality of dielectric layers and internal electrodes having different polarities are alternately stacked while being interposed between the dielectric layers.

In this case, since the dielectric layers have piezoelectric properties, when a direct current (DC) voltage or an alternating current (AC) voltage is applied to the multilayer ceramic capacitor, a piezoelectric phenomenon may be generated between the internal electrodes, such that a volume of a ceramic body is expanded and contracted according to a frequency, thereby generating periodic vibrations.

The vibrations are transmitted to a printed circuit board through external electrodes and a solder connecting the external electrodes of the multilayer ceramic capacitor to the printed circuit board, such that the entire printed circuit board becomes a sound reflective surface to generate a vibration sound to be a noise.

The vibration sound may be in an audible frequency region of 20 to 20,000 Hz, causing listener discomfort, and the vibration sound causing listener discomfort refers to an acoustic noise.

Recently, in electronic devices, since acoustic noise generated in the multilayer ceramic capacitor as described above may be significant due to a decreased noise of components, research into a technology of effectively decreasing the acoustic noise generated in the multilayer ceramic capacitor has been required.

As a method of decreasing the acoustic noise as described above, a method of attaching frame-shaped metal terminals to both end surfaces of the multilayer ceramic capacitor and mounting the multilayer ceramic capacitor on the printed circuit board so as to be spaced apart therefrom by a predetermined interval has been disclosed.

However, in order to decrease the acoustic noise to a predetermined level using the metal terminals, it is necessary to increase a thickness of the metal terminals to a predetermined standard or more.

In this case, since the increase in the thickness of the metal terminals as described above may increase a thickness of a

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component in which the multilayer ceramic capacitor is mounted, the increase in the thickness of the metal terminals may not be applied to a product having a limitation in the thickness thereof.

The following Patent Document 1 discloses a method of decreasing acoustic noise transmitted from a multilayer ceramic capacitor to a printed circuit board, using a metal terminal, but fails to disclose a method of decreasing a size (thickness) of a component having the multilayer ceramic capacitor mounted thereon.

RELATED ART DOCUMENT

(Patent Document 1) Korean Patent Laid-Open Publication No. KR 2012-0106599

SUMMARY OF THE INVENTION

An aspect of the present invention provides a multilayer ceramic capacitor capable of effectively decreasing acoustic noise occurring when vibrations generated in the multilayer ceramic capacitor by a piezoelectric phenomenon are transmitted to a printed circuit board, without an increase in a thickness of a product having the multilayer ceramic capacitor mounted therein.

According to an aspect of the present invention, there is provided a multilayer ceramic capacitor including: a ceramic body having a plurality dielectric layers stacked therein and a groove portion recessed inwardly in a lower surface thereof in a width direction, a plurality of first and second internal electrodes disposed in the ceramic body to be alternately exposed through both end surfaces of the ceramic body, having the dielectric layers therebetween, and first and second external electrodes respectively formed on both end portions of the ceramic body and electrically connected to the first and second internal electrodes, respectively.

The multilayer ceramic capacitor may further include first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a length direction, centered on the groove portion.

The first and second dummy electrodes may be respectively exposed through the both end surfaces of the ceramic body and be connected to the first and second external electrodes, respectively.

The first and second dummy electrodes may be spaced apart from the first and second external electrodes.

The multilayer ceramic capacitor may further include first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a length direction, centered on the groove portion, the lower margin part having a thickness greater than that of an upper margin part of the ceramic body.

The first and second dummy electrodes may be respectively exposed through the both end surfaces of the ceramic body and be connected to the first and second external electrodes, respectively.

The multilayer ceramic capacitor may further include first and second dummy patterns formed in the ceramic body to face the first and second internal electrodes while being spaced apart from the first and second internal electrodes in a length direction, respectively, and connected to the second and first external electrodes, respectively.

According to another aspect of the present invention, there is provided a multilayer ceramic capacitor including: a ceramic body having a plurality dielectric layers stacked therein and a groove portion recessed inwardly in a lower surface thereof in a length direction; a plurality of first and

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second internal electrodes disposed in the ceramic body to be alternately exposed through both end surfaces of the ceramic body, having the dielectric layers therebetween; and first and second external electrodes respectively formed on both end portions of the ceramic body and electrically connected to the first and second internal electrodes, respectively.

The multilayer ceramic capacitor may further include first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a width direction, centered on the groove portion.

The first and second dummy electrodes may be respectively exposed through the both end surfaces of the ceramic body and be connected to the first and second external electrodes, respectively, and may include first and second exposed parts respectively exposed through the both end surfaces of the ceramic body; and pairs of extension parts protruded from ends of the first and second exposed parts to be perpendicular thereto, inwardly in the ceramic body in the length direction thereof.

The multilayer ceramic capacitor may further include first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a width direction, centered on the groove portion, the lower margin part having a thickness greater than that of an upper margin part of the ceramic body.

The first and second dummy electrodes may be respectively exposed through the both end surfaces of the ceramic body and connected to the first and second external electrodes, respectively. Lengths of the first and second dummy electrodes may be increased in an upward direction from a lower surface of the ceramic body. The first and second dummy electrodes may be formed in a stepped manner, in an upward direction from the lower surface of the ceramic body.

According to another aspect of the present invention, there is provided a manufacturing method of a multilayer ceramic capacitor, the manufacturing method including: preparing a stacked body having an inwardly recessed portion positioned between first and second dummy electrodes by stacking a plurality of ceramic sheets having first and second internal electrodes formed therein to face each other, having the ceramic sheets therebetween and stacking thereon, a plurality of ceramic sheets having the first and second dummy electrodes formed therein to face each other, having a predetermined interval therebetween, and pressing the plurality of ceramic sheets; preparing a ceramic body such that the first and second dummy electrodes are respectively exposed through both end surfaces thereof and the first and second internal electrodes are alternately exposed through both end surfaces thereof, by cutting the stacked body into portions, each corresponding one capacitor, and firing the portion; and forming first and second external electrodes in the ceramic body to be electrically connected to the first and second internal electrodes, respectively.

In the preparing of the stacked body, the first and second dummy electrodes may be disposed to face each other in a length direction of the ceramic body.

In the preparing of the stacked body, the first and second dummy electrodes may be disposed to face each other in a width direction of the ceramic body.

According to another aspect of the present invention, there is provided a mounting board of a multilayer ceramic capacitor, the mounting board including: a printed circuit board having first and second electrode pads disposed thereon; and at least one multilayer ceramic capacitor mounted on the printed circuit board, wherein the multilayer ceramic capacitor includes: a ceramic body having a plurality dielectric layers stacked therein and a groove portion recessed inwardly

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in a mounting surface thereof in a width direction; a plurality of first and second internal electrodes disposed in the ceramic body to be alternately exposed through both end surfaces of the ceramic body, having the dielectric layers therebetween; and first and second external electrodes respectively formed on both end portions of the ceramic body, electrically connected to the first and second internal electrodes, respectively, and connected to the first and second electrode pads by a solder.

BRIEF DESCRIPTION OF THE DRAWINGS

The above and other aspects, features and other advantages of the present invention will be more clearly understood from the following detailed description taken in conjunction with the accompanying drawings, in which:

FIG. 1 is a perspective view schematically showing a multilayer ceramic capacitor according to an embodiment of the present invention;

FIG. 2 is a bottom view of FIG. 1;

FIGS. 3A through 3C are perspective views respectively showing first and second internal electrodes and dummy electrodes applied to the multilayer ceramic capacitor of FIG. 1;

FIG. 4 is a cross-sectional view of the multilayer ceramic capacitor, taken along line A-A' of FIG. 1;

FIGS. 5A and 5B are side cross-sectional views showing a method of forming a groove portion in a mounting surface of a ceramic body in a manufacturing method of the multilayer ceramic capacitor according to the embodiment of the present invention;

FIG. 6 is a side cross-sectional view schematically showing a state in which the multilayer ceramic capacitor according to the embodiment of the present invention is applied to a mounting board;

FIG. 7 is a perspective view schematically showing a multilayer ceramic capacitor according to another embodiment of the present invention;

FIG. 8 is a bottom view of FIG. 7;

FIG. 9 is a cross-sectional view of the multilayer ceramic capacitor, taken along line B-B' of FIG. 7;

FIGS. 10A through 10C are perspective views respectively showing first and second internal electrodes and dummy electrodes applied to the multilayer ceramic capacitor of FIG. 7;

FIG. 11 is a perspective view showing another example of the dummy electrode applied to the multilayer ceramic capacitor of FIG. 7;

FIG. 12 is a perspective view showing another example of the dummy electrode applied to the multilayer ceramic capacitor of FIG. 7; and

FIGS. 13 through 16 are side cross-sectional views respectively showing another example of the multilayer ceramic capacitor according to the present invention.

DETAILED DESCRIPTION OF THE EMBODIMENTS

Hereinafter, embodiments of the present invention will be described in detail with reference to the accompanying drawings.

The invention may, however, be embodied in many different forms and should not be construed as being limited to the embodiments set forth herein.

Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the invention to those skilled in the art.

In the drawings, the shapes and dimensions of elements may be exaggerated for clarity.

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The same reference numerals will be used throughout to designate the same or like elements.

Multilayer Ceramic Capacitor

FIG. 1 is a perspective view schematically showing a multilayer ceramic capacitor according to an embodiment of the present invention, FIG. 2 is a bottom view of FIG. 1, FIGS. 3A through 3C are perspective views respectively showing first and second internal electrodes and dummy electrodes applied to the multilayer ceramic capacitor of FIG. 1, and FIG. 4 is a cross-sectional view of the multilayer ceramic capacitor, taken along line A-A' of FIG. 1.

Referring to FIGS. 1 through 4, a multilayer ceramic capacitor **100** according to the present embodiment may include a ceramic body **110** including a plurality of dielectric layers **111** stacked therein, a plurality of first and second internal electrodes **121** and **122**, and first and second external electrodes **131** and **132** electrically connected to the first and second internal electrodes **121** and **122**, respectively.

The ceramic body **110** may be formed by stacking the plurality of dielectric layers **111** in a thickness direction thereof and performing firing thereon, wherein boundaries between adjacent dielectric layers **111** may be integrated such that they may not be readily discernible.

In addition, the ceramic body **110** may have a hexahedral shape. In the present embodiment, surfaces of the ceramic body **110** facing each other in the thickness direction, that is, in a direction in which the dielectric layers **111** of the ceramic body **110** are stacked, are defined as first and second main surfaces **1** and **2**, surfaces connecting the first and second main surfaces **1** and **2** and facing each other in a length direction may be defined as third and fourth end surfaces **3** and **4**, and surfaces facing each other in a width direction may be defined as fifth and sixth side surfaces **5** and **6**.

In the present embodiment, the second main surface **2** of the ceramic body **110**, a mounting surface of the multilayer ceramic capacitor **100** may be provided with a groove portion **170** recessed inwardly in a width direction.

The dielectric layer **111** may include a ceramic material having a high dielectric constant, and for example, a barium titanate (BaTiO_3)-based ceramic powder, or the like, but the present invention is not limited thereto as long as sufficient capacitance is obtained thereby.

Furthermore, the dielectric layers **111** may include a ceramic powder and if necessary, further include various types of ceramic additives such as a transition metal oxide or transition metal carbide, rare earth elements, and magnesium (Mg) or aluminum (Al), an organic solvent, a plasticizer, a binder and a dispersant, along with the ceramic powder.

The first and second internal electrodes **121** and **122**, which are electrodes having different polarities, may be stacked on at least one surface of a ceramic sheet forming the dielectric layer **111**, and may be disposed in the ceramic body **100** so as to be alternately exposed through the third and fourth end surfaces **3** and **4**, having the dielectric layer **111** therebetween.

In this case, the first and second internal electrodes **121** and **122** may be electrically insulated from each other by the dielectric layers **111** disposed therebetween.

Capacitance of the multilayer ceramic capacitor **100** may be proportional to an area of the first and second internal electrodes **121** and **122** overlapped with each other in the stacking direction of the dielectric layers **111**.

That is, the first and second internal electrodes **121** and **122** may be continuously stacked in the thickness direction to configure an active region for forming the capacitance in the ceramic body **110**.

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In addition, in a cross-section of the multilayer ceramic capacitor **100** in a length-thickness direction, portions except for the active region may be defined as margin parts.

Among the margin parts, margin parts positioned on an upper portion and a lower portion of the active region in the thickness direction may be formed by stacking a plurality of upper and lower cover layers **112** and **113** having no internal electrodes formed therein.

The upper and lower cover layers **112** and **113** may be formed by sintering ceramic sheets in a similar manner to that of the dielectric layer **111** having the first and second internal electrodes **121** and **122** formed therein.

The upper and lower margin parts are formed such that the plurality of upper and lower cover layers **112** and **113** are sintered and may be integrated so as not to confirm boundaries between the upper and lower cover layers **112** and **113** adjacent to each other.

In the present embodiment, the lower margin part has a thickness greater than that of the upper margin part.

That is, the lower margin part may have the thickness greater than that of the upper margin part by increasing the number of the ceramic sheets stacked in the lower cover layer as compared to the upper margin part, and in this manner, in the case in which the active region is spaced apart from the mounting surface, vibrations generated in the multilayer ceramic capacitor **100** and transmitted to a board at the time of mounting the multilayer ceramic capacitor **100** on the board may be decreased.

However, the present invention is not limited thereto, but may be changed in various manners in which the upper margin part has a thickness greater than that of the lower margin part or the upper margin part and the lower margin part have the same thickness in a range satisfying a standard range of a product.

In addition, the first and second internal electrodes **121** and **122** may be formed of a conductive metal, for example, one of silver (Ag), palladium (Pd), platinum (Pt), nickel (Ni), and copper (Cu), alloys thereof, or the like, but the present invention is not limited thereto.

The first and second external electrodes **131** and **132** may be extended from the third and fourth end surfaces **3** and **4** of the ceramic body **110** to the surfaces **1**, **2**, **5**, and **6** adjacent thereto so as to be electrically connected to the first and second internal electrodes **121** and **122** by covering the plurality of first and second internal electrodes **121** and **122** exposed through the third and fourth end surfaces **3** and **4**, respectively.

In addition, the first and second external electrodes **131** and **132** may be formed of a conductive metal, for example, one of silver (Ag), palladium (Pd), platinum (Pt), nickel (Ni), and copper (Cu), alloys thereof, or the like, but the present invention is not limited thereto.

In this case, the first and second external electrodes **131** and **132** may have first and second plating layers (not shown) formed thereon, as needed.

The first and second plating layers may include a nickel (Ni) plating layer formed on the first and second external electrodes **131** and **132** and a tin (Sn) plating layer formed on the nickel plating layer.

The first and second plating layers are provided to increase adhesion strength between the multilayer ceramic capacitor **100** and a printed circuit board at the time of mounting the multilayer ceramic capacitor **100** on the printed circuit board, or the like, by solder, or the like. The plating may be performed by a method known in the art.

Meanwhile, the lower cover layer **113** forming the lower margin part of the ceramic body **110** may have a plurality of

first and second dummy electrodes **123** and **124** formed therein to face each other with a predetermined gap **113a** therebetween in the length direction centered on the groove portion **170**. The gap **113a** is a component required for forming the groove portion **170** in a compression process, and a detailed description thereof will be described in a manufacturing method as described below.

In this case, the first and second dummy electrodes **123** and **124** may be exposed through the third and fourth end surfaces **3** and **4** of the ceramic body **110** to be connected to the first and second external electrodes **131** and **132**, respectively.

In addition, as another example, referring to FIG. **14**, first and second dummy electrodes **123'** and **124'** may not be exposed through the third and fourth end surfaces **3** and **4** of the ceramic body **110** and may be included in the ceramic body **110** to be spaced apart from the first and second external electrodes **131** and **132**, respectively.

Referring to FIGS. **13** and **14**, the ceramic body **110** may further include first and second dummy patterns **141** and **142** formed therein to face the first and second internal electrodes **121** and **122** in the length direction while being spaced apart from the first and second internal electrodes **121** and **122**, respectively.

In this case, the first and second dummy patterns **141** and **142** may be exposed through the both end surfaces of the ceramic body **110**, respectively, such that end portions of the first and second dummy patterns are connected to the second external electrode **132** and the first external electrode **131**, respectively.

Manufacturing Method of Multilayer Ceramic Capacitor

Hereinafter, a manufacturing method of the multilayer ceramic capacitor according to the embodiment of the present invention will be described.

First, a plurality of ceramic sheets are prepared. The ceramic sheets are provided to form the dielectric layers **111** of the ceramic body **110** and the upper and lower cover layers **112** and **113** of upper and lower margin parts of the ceramic body **110** and may be manufactured by mixing a ceramic powder, a polymer, a solvent, and the like to prepare a slurry, and then applying and drying the slurry onto carrier films to form the slurry in sheet shapes each having a thickness of several μm by a doctor blade method or the like.

Next, the first and second internal electrodes **121** and **122** are formed by printing a conductive paste at a predetermined thickness on at least one surface of the plurality of respective ceramic sheets.

Here, the first and second internal electrodes **121** and **122** are exposed through the both end surfaces of the ceramic sheets in the length direction, respectively.

Methods of printing the conductive paste may include a screen printing method, a gravure printing method, and the like, but the present invention is not limited thereto.

Further, the conductive paste is printed at a predetermined thickness on at least one surface of a portion of the ceramic sheets, such that the first and second dummy electrodes **123** and **124** may be formed to face each other, having a predetermined interval therebetween.

In this case, the first and second dummy electrodes **123** and **124** may be disposed to face each other in the length direction of the ceramic sheet.

The first and second dummy electrodes **123** and **124** may be disposed in the lower margin part, and do not have a structure in which the internal electrodes having different polarities are overlapped with each other, having the ceramic sheets therebetween.

Therefore, the first and second dummy electrodes **123** and **124** may not contribute to the formation of capacitance except

for a parasitic capacitance generated by influences of the first and second external electrodes **131** and **132** on the third and fourth end surfaces **3** and **4** of the ceramic body **110** or the active region for forming capacitance.

Then, the plurality of ceramic sheets having the first and second dummy electrodes **123** and **124** formed therein are stacked, the plurality of ceramic sheets having the first and second internal electrodes **121** and **122** formed therein are stacked thereon in such a manner that the first and second internal electrodes **121** and **122** face each other, having the ceramic sheets therebetween, and then, the plurality of ceramic sheets having no electrodes formed therein are stacked thereon.

In this case, the plurality of ceramic sheets may be stacked in an asymmetric manner in which the lower margin part configured of the plurality of ceramic sheets having the first and second dummy electrodes **123** and **124** formed therein has a thickness greater than that of the upper margin part configured of the plurality of ceramic sheets having no electrodes formed therein.

In general, in a case in which the ceramic body **110** has the upper margin part and the lower margin part formed in an asymmetric manner, since the active region having the first and second internal electrodes **121** and **122** and the lower margin part disposed therebelow have a difference in shrinkage rates when they are sintered and shrunk in a firing process, delamination or crack defects may be increased.

However, in the present embodiment, since the first and second dummy electrodes **123** and **124** are formed in the lower margin part, the difference in shrinkage rates between the active region and the lower margin part is decreased, such that the delamination or crack defects may be decreased or even though the delamination is generated, the delamination is generated in the dummy electrode rather than the internal electrode, thereby increasing reliability of a product.

Then, as shown in FIG. **5A**, the ceramic sheets stacked as described above are disposed on a flat metal plate **300** in such a manner that the ceramic sheets having the first and second dummy electrodes **123** and **124** formed therein are arranged in an upper portion thereof, and then the disposed ceramic sheets are pressed in downward and inward directions to thereby prepare a stacked body.

In this case, as shown in FIG. **5B**, one surface of the stacked body, that is, a portion of the second main surface **2**, positioned between the first and second dummy electrodes **123** and **124** is recessed inwardly due to force supported by the first and second dummy electrodes **123** and **124**, such that the groove portion **170** may be formed therein.

Therefore, the groove portion **170** may be formed in a direction perpendicular to directions in which the first and second dummy electrodes **123** and **124** face each other.

That is, in the case in which the first and second dummy electrodes **123** and **124** face each other in the length direction, the groove portion may be extended in the width direction, and in the case in which the first and second dummy electrodes **123** and **124** face each other in the width direction, the groove portion may be extended in the length direction.

Then, the stacked body is cut into portions, each corresponding to one capacitor chip, and then the portions are fired at a high temperature to prepare the ceramic bodies **110** each having first and second main surfaces **1** and **2** facing each other in the thickness direction, third and fourth end surfaces **3** and **4** facing each other in the length direction and having the first and second internal electrodes **121** and **122** alternately exposed thereto, and fifth and sixth side surfaces **5** and **6** facing each other in the width direction.

Next, the first and second external electrodes **131** and **132** are formed on the end surfaces of the ceramic body **110** in a thickness-length direction so as to be electrically connected to exposed portions of the first and second internal electrodes **121** and **122**.

Here, after forming the first and second external electrodes **131** and **132**, a plating process such as an electroplating process may be performed on surfaces of the first and second external electrodes **131** and **132**, such that first and second plating layers (not shown) may be formed, as needed.

Examples of materials used in the plating process may include nickel or tin, a nickel-tin-alloy, and the like, but the present invention is not limited thereto.

In addition, the first and second plating layers may have a two-layer structure by sequentially stacking a nickel plating layer and a tin plating layer on the surfaces of the first and second external electrodes **131** and **132**, as needed.

FIG. **6** is a side cross-sectional view schematically showing a state in which the multilayer ceramic capacitor according to the embodiment of the present invention is applied to a mounting board.

Referring to FIG. **6**, the mounting board to which the multilayer ceramic capacitor **100** is applied may include a printed circuit board **210** having the multilayer ceramic capacitor **100** mounted thereon, and first and second electrode pads **220** formed on the printed circuit board **210** to be spaced apart from each other.

In this case, the multilayer ceramic capacitor **100** may be mounted on the printed circuit board **210** such that the second main surface **2** of the ceramic body **110** having the groove portion **170** formed therein faces the printed circuit board **210**, and the first and second external electrodes **131** and **132** may be electrically connected to the printed circuit board **210** by a solder **230** while being positioned on the first and second electrode pads **220** to contact therewith, respectively.

In the case in which voltages having different polarities are applied to the first and second external electrodes **131** and **132** of the multilayer ceramic capacitor **100** in a state in which the multilayer ceramic capacitor **100** is mounted on the printed circuit board **210** as described above, the ceramic body **110** may be repeatedly expanded and shrunk in the thickness direction due to an inverse piezoelectric effect of the dielectric layers **111** to generate the vibrations (see white arrows of FIG. **6**).

In this case, since piezoelectric stress generated in the ceramic body **110** due to the groove portion **170** recessed inwardly in the second main surface **2** of the ceramic body **110** is dispersed and suppressed, as shown in 'black arrows' of FIG. **6** and only a small amount of piezoelectric stress is transmitted to the printed circuit board **210** through the solder **230**, acoustic noise may be decreased.

MODIFIED EXAMPLE

FIG. **7** is a perspective view schematically showing a multilayer ceramic capacitor according to another embodiment of the present invention. FIG. **8** is a bottom view of FIG. **7**. FIG. **9** is a cross-sectional view of the multilayer ceramic capacitor, taken along line B-B' of FIG. **7**. FIGS. **10A** through **10C** are perspective views respectively showing first and second internal electrodes and dummy electrodes applied to the multilayer ceramic capacitor of FIG. **7**.

In this case, since a structure in which the first and second internal electrodes **121** and **122** and the first and second external electrodes **131** and **132** are formed is similar to the structure as described in the foregoing embodiment of the present invention, a detailed description thereof will be omitted

in order to avoid a repeated explanation, and only a groove portion **170'** and first and second dummy electrodes having different structures from those as described in the foregoing embodiment of the present invention will be described in detail.

Referring to FIGS. **7** through **10**, in a multilayer ceramic capacitor **100'** according to the present embodiment, the groove portion **170'** of the ceramic body **110'** may be formed in the length direction of the ceramic body **110'**. In the case in which the groove portion **170'** is formed in the length direction, an area of the groove portion **170'** is larger than that of the case in which the groove portion is formed in the width direction, such that stress may be further effectively dispersed.

Therefore, first and second dummy electrodes **125** and **126** may be formed in the lower cover layer **113** to face each other in the width direction, having a predetermined interval therebetween.

FIGS. **11** and **12** are perspective views respectively showing another example of the dummy electrode applied to the multilayer ceramic capacitor **100'** according to the present embodiment.

For example, referring to FIG. **11**, first and second dummy electrodes **127** and **128** may include first and second exposed parts **127a** and **128a** exposed through the third and fourth end surfaces **3** and **4** of the ceramic body **110**, respectively; and pairs of extension parts **127b** and **128b** protruded from ends of the first and second exposed parts **127a** and **128a** to be perpendicular thereto, inwardly in the ceramic body **110** in the length direction thereof. In the structure as described above, the groove portion is formed in both of the length direction and the width direction, such that the stress is simultaneously dispersed in the length direction and the width direction and is further effectively dispersed.

In addition, referring to FIG. **12**, first and second dummy electrodes **129a** and **129b** may be configured of floating electrodes not in contact with the first and second external electrodes **131** and **132** but facing each other in the lower cover layer **113**. In this case, since the first and second dummy electrodes **129a** and **129b** are not electrically connected to the first and second external electrodes **131** and **132**, stray capacitance between the printed circuit board and the external electrodes is decreased, such that high frequency properties may be improved.

Meanwhile, referring to FIG. **15**, in a multilayer ceramic capacitor **100''** of the present embodiment, a plurality of first and second dummy electrodes **125'** and **126'** may have different lengths in the thickness direction and the lengths thereof are increased in an upward direction from a lower surface of the ceramic body **110''** in which the groove portion **170'** is formed, such that a margin part **180** formed between the first and second dummy electrodes **125'** and **126'** may have a tapered shape in which the margin part is narrowed in the upward direction.

In addition, referring to FIG. **16**, in the multilayer ceramic capacitor **100''** of the present embodiment, the plurality of first and second dummy electrodes **125a**, **125b**, **126a**, and **126b** may have different lengths in the thickness direction and the lengths thereof may be varied such that the dummy electrodes are formed in a stepped manner, in the upward direction from the lower surface of the ceramic body **110'** in which the groove portion **170'** is formed, whereby the margin part **180** may have a stepped shape in which the margin part is narrowed in an upward direction.

As set forth above, according to the embodiments of the present invention, a groove portion is formed in a mounting surface of a multilayer ceramic capacitor to be recessed

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inwardly therein, whereby piezoelectric stress generated in the multilayer ceramic capacitor at the time of mounting the multilayer ceramic capacitor on a printed circuit board can be dispersed and suppressed without an increase in a thickness (height) of a product having the multilayer ceramic capacitor 5 mounted therein. Thus, vibrations transferred to the printed circuit board through a solder are decreased to reduce acoustic noise.

While the present invention has been shown and described in connection with the embodiments, it will be apparent to those skilled in the art that modifications and variations can be made without departing from the spirit and scope of the invention as defined by the appended claims.

What is claimed is:

1. A multilayer ceramic capacitor, comprising:
 - a ceramic body having a plurality of dielectric layers stacked therein in a thickness direction and a groove portion recessed in a lower surface thereof toward the thickness direction, wherein the groove portion extends in a width direction;
 - a plurality of first and second internal electrodes disposed in the thickness direction in the ceramic body to be alternately exposed through both end surfaces of the ceramic body, having the dielectric layers therebetween; and
 - first and second external electrodes respectively formed on both end portions of the ceramic body and electrically connected to the first and second internal electrodes, respectively.
2. The multilayer ceramic capacitor of claim 1, further comprising first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a length direction, centered on the groove portion.
3. The multilayer ceramic capacitor of claim 2, wherein the first and second dummy electrodes are respectively exposed through the both end surfaces of the ceramic body and connected to the first and second external electrodes, respectively.
4. The multilayer ceramic capacitor of claim 2, wherein the first and second dummy electrodes are spaced apart from the first and second external electrodes.
5. The multilayer ceramic capacitor of claim 1, further comprising first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a length direction, centered on the groove portion, the lower margin part having a thickness greater than that of an upper margin part of the ceramic body.
6. The multilayer ceramic capacitor of claim 5, wherein the first and second dummy electrodes are respectively exposed through the both end surfaces of the ceramic body and connected to the first and second external electrodes, respectively.
7. The multilayer ceramic capacitor of claim 5, wherein the first and second dummy electrodes are spaced apart from the first and second external electrodes.
8. The multilayer ceramic capacitor of claim 1, further comprising first and second dummy patterns formed in the ceramic body to face the first and second internal electrodes while being spaced apart from the first and second internal electrodes in a length direction, respectively, and connected to the second and first external electrodes, respectively.
9. A multilayer ceramic capacitor comprising:
 - a ceramic body having a plurality of dielectric layers stacked therein in a thickness direction and a groove portion recessed in a lower surface thereof toward the thickness direction, wherein the groove portion extends in a length direction;

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a plurality of first and second internal electrodes disposed in the thickness direction in the ceramic body to be alternately exposed through both end surfaces of the ceramic body, having the dielectric layers therebetween; and

first and second external electrodes respectively formed on both end portions of the ceramic body and electrically connected to the first and second internal electrodes, respectively.

10. The multilayer ceramic capacitor of claim of claim 9, further comprising first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a width direction, centered on the groove portion.

11. The multilayer ceramic capacitor of claim 10, the first and second dummy electrodes are respectively exposed through the both end surfaces of the ceramic body and connected to the first and second external electrodes, respectively.

12. The multilayer ceramic capacitor of claim 11, wherein lengths of the first and second dummy electrodes are increased in an upward direction from a lower surface of the ceramic body.

13. The multilayer ceramic capacitor of claim 11, wherein the first and second dummy electrodes are formed in a stepped manner, in an upward direction from the lower surface of the ceramic body.

14. The multilayer ceramic capacitor of claim 10, wherein the first and second dummy electrodes are spaced apart from the first and second external electrodes.

15. The multilayer ceramic capacitor of claim 10, wherein the first and second dummy electrodes include first and second exposed parts respectively exposed through the both end surfaces of the ceramic body; and pairs of extension parts protruded from ends of the first and second exposed parts to be perpendicular thereto, inwardly in the ceramic body in the length direction thereof.

16. The multilayer ceramic capacitor of claim 9, further comprising first and second dummy electrodes formed in a lower margin part of the ceramic body to face each other in a width direction, centered on the groove portion, the lower margin part having a thickness greater than that of an upper margin part of the ceramic body.

17. The multilayer ceramic capacitor of claim 16, wherein the first and second dummy electrodes are respectively exposed through the both end surfaces of the ceramic body and connected to the first and second external electrodes, respectively.

18. The multilayer ceramic capacitor of claim 16, wherein the first and second dummy electrodes are spaced apart from the first and second external electrodes.

19. A manufacturing method of a multilayer ceramic capacitor, the manufacturing method comprising:

preparing a stacked body having an inwardly recessed portion positioned between first and second dummy electrodes by stacking a plurality of ceramic sheets having first and second internal electrodes formed therein to face each other, having the ceramic sheets therebetween and stacking thereon, a plurality of ceramic sheets having the first and second dummy electrodes formed therein to face each other, having a predetermined interval therebetween, and pressing the plurality of ceramic sheets;

preparing a ceramic body such that the first and second dummy electrodes are respectively exposed through both end surfaces thereof and the first and second internal electrodes are alternately exposed through both end

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surfaces thereof, by cutting the stacked body into portions, each corresponding one capacitor, and firing the portion; and

forming first and second external electrodes in the ceramic body to be electrically connected to the first and second internal electrodes, respectively. 5

20. The manufacturing method of claim **19**, wherein in the preparing of the stacked body, the first and second dummy electrodes are disposed to face each other in a length direction of the ceramic body. 10

21. The manufacturing method of claim **19**, wherein in the preparing of the stacked body, the first and second dummy electrodes are disposed to face each other in a width direction of the ceramic body.

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